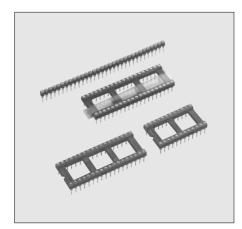
# Panasonic ideas for life

# HIGH RELIABILITY IC SOCKET WITH ROUND PIN

## ROUND PIN TYPE IC SOCKETS



#### **FEATURES**

- 1. With advanced design method of the frame, stress transmission from the PC board is greatly reduced.
- 2. This is a high reliability IC socket with round pin external contacts constructed with 4 point internal contacts.

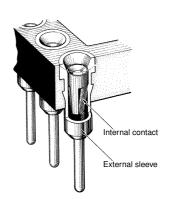
Because of the gold plating on all surfaces, the 4 point contact construction offers superior resistance to vibration, shock, and environmental conditions, resulting in high reliability.

- 3. Terminal shape prevents entrance of solder flux. Because of the round pin construction and sufficient distance being provided between the PC board mounting surface and the frame, flux cannot rise up into the contact section.
- 4. Water-washable sealed types also available

As the sealed type uses hot-melt tape, there is a strong bond between the tape and molded product, which will prevent cleaning fluid from entering even if a 3-bath cleaning (boiling, ultrasonic, vapor) is used.

**5. Compliance with RoHS' Directive** Environmentally friendly, the connectors' comply with Europe's RoHS' Directive. Cadmium, lead, mercury, hexavalent, chromium, PBB and PBDE are not used.

## CONSTRUCTION OF CONTACT



#### ORDERING INFORMATION

**AXS** 10: Round PIN type IC sockets <No. of contacts (2 digits)> 08: 8 contacts 14: 14 contacts 16: 16 contacts 18: 18 contacts 20: 20 contacts 22: 22 contacts 24: 24 contacts 28: 28 contacts 32: 32 contacts 36: 36 contacts 40: 40 contacts 48: 48 contacts 64: 64 contacts <Terminal layout and shape> 1: DIL terminal layout, solder DIP terminal 2: SIL terminal layout, solder DIP terminal 7: DIL terminal layout, solder DIP terminal (24 contacts: row pitch is 7.62 mm) <Surface treatment (Internal contact/External sleeve)> 1: Au plating 0.25µm/Sn plating 3: Au plating 0.76µm/Sn plating 7: Au plating 0.76µm/Au plating 9: Sn plating/Sn plating

### **PRODUCT TYPES**

#### 1. Solder dip terminal type

Item		Economical type (Extremely resistant to fretting with IC)	General-purpose type (Extremely resistant to fretting with IC)	High-reliability type (Contact resistance is stable even if left unadhered for extended periods.)	Testing use	Pack	aging
External sleeve		Sn plating			Au plating		
Internal contact		Sn plating	Au plating (0.25μm)	Au plating (0.76μm)	Au plating (0.76μm)		
Type	No. of contacts	Part No.	Part No.	Part No.	Part No.	Inner carton (Stick)	Outer carton
	8	AXS100819	AXS100811	AXS100813	AXS100817	50 pcs.	300 pcs.
	14	AXS101419	AXS101411	AXS101413	AXS101417	25 pcs.	300 pcs.
	16	AXS101619	AXS101611	AXS101613	AXS101617	25 pcs.	300 pcs.
	18	AXS101819	AXS101811	AXS101813	AXS101817	20 pcs.	300 pcs.
	20	AXS102019	AXS102011	AXS102013	AXS102017	20 pcs.	300 pcs.
	22	AXS102219	AXS102211	AXS102213	AXS102217	15 pcs.	300 pcs.
DIL	24*1	AXS102419	AXS102411	AXS102413	AXS102417	15 pcs.	300 pcs.
DIL	24*2	AXS102479	AXS102471	AXS102473	AXS102477	15 pcs.	300 pcs.
	28	AXS102819	AXS102811	AXS102813	AXS102817	15 pcs.	300 pcs.
	32	AXS103219	AXS103211	AXS103213	AXS103217	10 pcs.	300 pcs.
	36	AXS103619	AXS103611	AXS103613	AXS103617	10 pcs.	300 pcs.
	40	AXS104019	AXS104011	AXS104013	AXS104017	10 pcs.	300 pcs.
	48	AXS104819	AXS104811	AXS104813	AXS104817	8 pcs.	200 pcs.
	64	AXS106419	AXS106411	AXS106413	AXS106417	5 pcs.	100 pcs.
SIL	32	AXS103229	AXS103221	AXS103223	AXS103227	10 pcs.	100 pcs.

<sup>\*1</sup> Pitch: 15.24mm

\*2 Pitch: 7.62mm Note) All are stick packaged.

#### **SPECIFICATIONS**

#### 1. Characteristics

	Item	Specifications	Condition	
	Rated current	1A		
Electrical characteristics	Breakdown voltage	1,000V AC for 1 min.	Detection current: 1mA	
	Insulation resistance	Min. 1,000MΩ	Using 500V DC megger	
	Contact resistance	Max. 20mΩ	Measured based on the HP4338B measurement method of JIS C 5402	
	Electrostatic capacitance	Max. 2pF	at 1kHz	
Mechanical characteristics	Vibration resistance	10 to 2,000Hz, 147m/s² {15G}	After carrying current (Max. 100mA) during the test, no interruption of current longer than 1µs does not occur.	
	Shock resistance	980m/s² {100G}	After carrying current (Max. 100mA) during the test, no interruption o current longer than 1µs does not occur.	
	Insertion force of single contact	Max. 3.33N {340gf}	Measured by steel-gauge with 0.4×0.25mm cross section area or by pingauge with diameter 0.4mm	
	Pull-out force of single contact	Min. 0.392N {40gf}	Measured by steel-gauge with 0.4×0.25mm cross section area or by pingauge with diameter 0.4mm	
	Insertion and removal life	Min. 100 times	With usage of applicable leads	
Applicable leads		Square lead: at 0.5±0.1×0.25±0.05 Round lead: Diameter 0.4 to 0.53mm		
	H₂S gas	Contact resistance after test: Max. 20mΩ	After 96 hours of exposure to himidity 75 to 80% R.H., temperature 40°C±2°C, concentration 3±1 ppm	
	SO <sub>2</sub> gas	Contact resistance after test: Max. 20mΩ	After 48 hours of exposure to himidity 90 to 95% R.H., temperature 40°C±2°C, concentration 10±3 ppm	
	Humidity	Contact resistance after test: Max. $20m\Omega$ Insulation resistance after test: Min. $300M\Omega$	After 96 hours of exposure to himidity 90 to 95% R.H., temperature 40°C±2°C	
Environmental resistance	Thermal shock resistance	Contact resistance after test: Max. $20m\Omega$ Insulation resistance after test: Min. $300M\Omega$	Low temperature: -55°C (30 min.) 1 cycle High temperature: +125°C (30 min.) 1 cycle No. of cycles: 5 cycles	
	Ambient temperature	Au plating: -55°C to +125°C Sn plating: -55°C to +85°C (No freezing at low temperature)		
	Soldering temperature	350°C: within 3 sec. 260°C: with 10 sec.		

#### 2. Materials and surface treatment

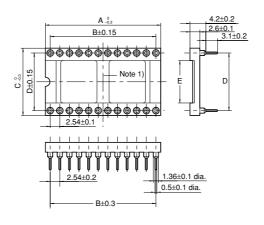
Part name Material		Surface treatment	
Frame	Glass-reinforced PBT (UL94V-0)	_	
External sleeve	Brass	Ni plating on base, Sn plating on surface or Ni plating on base, Au plating on surface	
Internal contact	Beryllium copper	Ni plating on base, Sn plating on surface Ni plating on base, Au plating on surface (0.25μm) Ni plating on base, Au plating on surface (0.76μm)	

<sup>•</sup> SIL type produced after order products: Supports up to 32 contacts. (Minimum order is 1,000 pieces)

#### **DIMENSIONS**

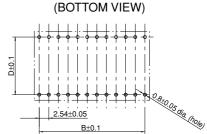
#### • DIL solder-DIP terminal type





## Recommended PC board pattern

mm General tolerance: ±0.3



Note) Rib is not provided for 8, 14 and 16 contacts; 1 rib is provided for 18, 20, 22, 24 and 28 contacts; 2 ribs are provided for 32, 36, 40 and 48 contacts; 4 ribs are provided for 64 contacts.

#### Dimension table (mm)

- ····································						
No. of contacts	Α	В	С	D	E	
8	10.16	7.62	10.16	7.62	4.3	
14	17.78	15.24	10.16	7.62	4.3	
16	20.32	17.78	10.16	7.62	4.3	
18	22.86	20.32	10.16	7.62	4.3	
20	25.4	22.86	10.16	7.62	4.3	
22	27.94	25.4	12.7	10.16	6.4	
24*1	30.48	27.94	17.78	15.24	11.2	
24*2	30.48	27.94	10.16	7.62	4.3	
28	35.56	33.02	17.78	15.24	11.2	
32	40.64	38.1	17.78	15.24	11.2	
36	45.72	43.18	17.78	15.24	11.2	
40	50.8	48.26	17.78	15.24	11.2	
48	60.96	58.42	17.78	15.24	11.2	
64	81.28	78.74	25.4	22.86	17.8	

<sup>\*1</sup> Pitch: 15.24mm \*2 Pitch: 7.62mm

#### • Rib layout (for DIL type)

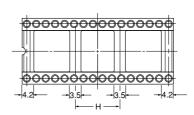
#### 8 to 16 contacts



#### Dimension table (mm)

No. of contacts	F
8	2.9
14	3.0
16	3.1

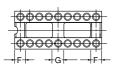
#### 32 to 48 contacts



#### Dimension table (mm)

No. of contacts	Н
32	11.5
36	13.5
40	15.5
48	15.5

#### 18 to 28 contacts

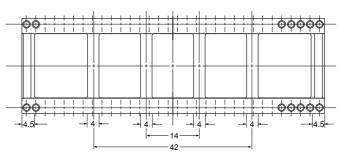


#### Dimension table (mm)

No. of contacts	F	G
18	3.5	3.0
20	3.5	3.0
22	3.7	3.0
24*1	4.0	3.2
24*2	4.2	3.0
28	4.0	3.2

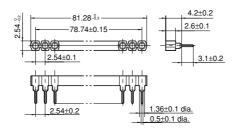
<sup>\*1</sup> Pitch: 15.24mm \*2 Pitch: 7.62mm

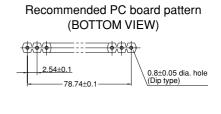
#### 64 contacts



#### SIL solder-DIP type (32 contacts)

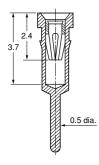






#### • Terminal (Common for DIL and SIL terminals)

Dip terminal



#### **NOTES**

- 1. Do not use for inserting of leads other than of applicable dimension. There is the possibility of distorting the internal contacts.
- 2. Because repeated flexing of the terminals can lead to the breakage of the terminal, care should be taken.
- 3. Soldering should be done under the following conditions.
- 260°C: Within 10 seconds soldering bath 350°C: Within 3 seconds soldering iron
- 4. Flux of the non-corroding rosin type should be used.
- 5. Liquid flux of minimum chemical action type alcohol can be used.
- 6. Sufficient care should be taken to prevent flux from entering the upper surface of the IC socket.
- 7. For mounting and removing the IC, a special tool for insertion and removal of IC's should be used.

Regarding general notes, please refer to page 12.

For other details, please verify with the product specification sheets.